

CLAIMS

1. An internal electrode paste, comprising electrode material powder, a binder resin containing a polyvinyl butyral resin and/or a polyvinyl acetal resin as the main component, and a solvent.

2. The internal electrode paste as set forth in claim 1, furthermore comprising a plasticizer, wherein said plasticizer is contained by 25 parts by weight or more and 150 parts by weight or less with respect to 100 parts by weight of said binder resin.

3. The internal electrode paste as set forth in claim 1 or 2, wherein said binder resin is contained by 2.5 to 5.5 parts by weight with respect to 100 parts by weight of said electrode material powder.

4. The internal electrode paste as set forth in any one of claims 1 to 3, furthermore comprising ceramic powder.

5. The internal electrode paste as set forth in claim 4, wherein said binder resin is contained by 2.5 to 5.5 parts by weight with respect to a total of 100 parts

by weight of said electrode material powder and ceramic powder.

6. The internal electrode paste as set forth in
5 any one of claims 1 to 5, wherein said electrode material powder is contained by 50 wt% or less with respect to the entire internal electrode paste.

7. The internal electrode paste as set forth in
10 any one of claims 1 to 6, wherein a polymerization degree of said polyvinyl butyral resin and/or a polyvinyl acetal resin is 1400 or more and 3600 or less.

8. The internal electrode paste as set forth in
15 any one of claims 1 to 7, wherein an acetalization degree of said polyvinyl acetal resin is 74 mol% or less.

9. A production method of an electronic device,
comprising the steps of:

20 preparing the internal electrode paste as set forth
in any one of claims 1 to 8;

forming a green sheet;

forming an internal electrode layer by using said
internal electrode layer paste;

25 stacking said green sheets via internal electrode

layers to obtain a green chip; and

firing said green chip.

10. A production method of an electronic device,
5 comprising the steps of:

forming an electrode layer on a surface of a first
supporting sheet by using the internal electrode paste as
set forth in any one of claims 1 to 8,;

10 pressing said electrode layer against a surface of
a green sheet and adhering said electrode layer to the
surface of said green sheet;

stacking the green sheet adhered with said
electrode layer to form a green chip; and

firing said green chip.

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